



# FCT Solder

## ECHA REACH COMPLIANCE

FCT Solder products are in compliance with ECHA REACH requirements for all substances of very high concern (SVHC). Our products do not contain any of the ingredients in the candidate list table, with some exceptions which are listed below.

[http://echa.europa.eu/chem\\_data/authorisation\\_process/candidate\\_list\\_table\\_en.asp](http://echa.europa.eu/chem_data/authorisation_process/candidate_list_table_en.asp)

This list has been updated through March, 2021.

Products which do contain materials in the SVHC candidate list.

Product	Chemical	CAS#	Concentration (% wt.)
WS890	2-[[[4-(2,4,4-trimethylpentan-2-yl)phenoxy]ethanol	9002-93-1	Flux gel (<3.0%) Solder paste (0.36%)
WS890	Bis(2-(2-methoxyethoxy)ethyl)ether (tetraglyme)	143-24-8	Flux gel (1.4%) Solder paste (0.16%)
NC650	Dibutyl phthalate (DBP)	84-74-2	Flux gel (0.79%) Solder paste (0.08%)
NL900	Dibutyl phthalate (DBP)	84-74-2	Flux gel (0.79%) Solder paste (0.09%)
NL900	Bis(2-(2-methoxyethoxy)ethyl)ether (tetraglyme)	143-24-8	Flux gel (13.1%) Solder paste (1.3%)
WS157	Dibutyl phthalate (DBP)	84-74-2	Flux gel (0.88%) Solder paste (0.10%)
Lead Containing Solder Pastes	Lead	7439-92-1	30-90% Lead is intentionally added to solder pastes at varying concentrations
RMA250	Bis(2-(2-methoxyethoxy)ethyl)ether (tetraglyme)	143-24-8	Flux gel (6.6%) Solder paste (0.67%)
NC676	Bis(2-(2-methoxyethoxy)ethyl)ether (tetraglyme)	143-24-8	Flux gel (7.0%) Solder paste (0.72%)
WS159	Bis(2-(2-methoxyethoxy)ethyl)ether (tetraglyme)	143-24-8	Flux gel (3.5%) Solder paste (0.37%)
WS888	Bis(2-(2-methoxyethoxy)ethyl)ether (tetraglyme)	143-24-8	Flux gel (1.4%) Solder paste (0.15%)

WIL-1	Bis(2-(2-methoxyethoxy)ethyl)ether (tetraglyme)	143-24-8	3.5%
Nitroflo Bar Solder	Lead	7439-92-1	37%

In addition, FCT Solder products do not contain carcinogenic, mutagenic, reproduction toxic substances as listed in Annex 1 to Directive 67/548/ EEC and in Annex VI to EU's CLP regulation.